

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Sep. 10, 2012

Expected First Date Code of Changed Product : 1226

Description of Change (From) :

Fairchild products manufactured on CS80CbiH30V process in Maine 6-inch class 1 fab.

Description of Change (To) :

In addition to Fairchild's 6-inch fab, products will be manufactured using Maine 8-inch class 1 fab. Die size, design geometry and layout of the affected products remain unchanged. Products manufactured on the 8-inch line will be fully compliant to all published datasheet specifications and will be completely interchangeable with the current product. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products. This process has been qualified and released in 2010. Most of the products using CS80CbiH30V process have been converted to 8-inch line.

Reason for Change:

Fairchild Semiconductor is increasing wafer capacity by qualifying the 8-inch line in South Portland, ME.

Affected Product(s):

FAN5331SX	FAN5333ASX	FAN5333BSX
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Qualification Plan	Device	Package	Process	No. of Lots
Q20080206	FAN5340MPX	MLDED008	CS80CBiH30V	3

Test Description:	Condition:	Standard :	Duration:	Results:
Autoclave	121C, 100%RH	JESD22-A102	168 hrs	0/231
Bond Pull		JESD22-C100		0/15
Bond Shear		AEC-Q100-001		0/15
Charged Device Model ESD	2.5kV	JESD22-A115		0/3
Die Shear		MIL-STD-883-2019		0/15
Dynamic Operation Life	125C, 5.5V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, 5.5V	JESD22-A110	96 hrs	0/135
Human Body Model ESD	3.5kV	JESD22-A114		0/3
Latch Up	8.25v, +/-300mA	JESD78		0/6
MSL1 Preconditioning		JESD22-A113		0/1059
Temperature Cycling	-65C, 150C	JESD22-A104	500 Cycles	0/231